DECLARATION AND POWER OF ATTERNET

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE HAVING NO CRACKS IN ONE OR MORE LAYERS UNDERLYING A METAL LINE LAYER AND METHOD OF MANUFACTURING THE SAME

the specification of which is attached hereto unless the following box is checked:

are apec							
□ wa		as United States Application Number or PCT International Application Number and was amended on (if applicable).					
	y state that I have reviewent referred to above.	wed and understand the contents of the above-identifi	ed specification, including the claims	, as amended by any			
	wledge the duty to discions § 1.56.	lose information which is known by me to be materi	al to patentability as defined in Title	37, Code of Federal			
inventor and hav that of t	r's certificate, or § 365(a)		at least one country other than the Unite	ed States, listed below			
	NUMBER	COUNTRY	DAY/MONTH/YEAR FILED	PRIORITY CLAIMED			
ngu	2001-8480	Republic of Korea	20/February/2001	Yes			
4. 1.							

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I hereby	y claim the benefit under	Title 35, United States Code § 119(e) of any United States	es provisional application(s) listed belo				
APPLICATION NO.			FILING DATE				
				· · ·			

I hereby claim the benefit under Title 35, United States Code, § 120 of any United States application(s), or § 365(c) of any PCT International application designating the United States, listed below and, insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States or PCT International application in the manner provided by the first paragraph of Title 35, United States Code, § 112, I acknowledge the duty to disclose information which is known by me to be material to patentability as defined in Title 37, Code of Federal Regulations § 1.56 which became available between the filing date of the prior application and the national or PCT International filing date of this application:

	

I hereby appoint as my attorneys, with full powers of substitution and revocation, to prosecute this application and transact all business in the Patent and Trademark Office connected therewith: Eugene M. Lee, Reg. No. 32,039; Richard A. Sterba, Reg. No. 43,162.

Address all correspondence to Eugene M. Lee, The Law Offices of Eugene M. Lee, PLLC, 2111 Wilson Boulevard, Suite 1200, Arlington, Virginia 22201. Address all telephone communications to Eugene M. Lee at (703) 525-0978.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

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